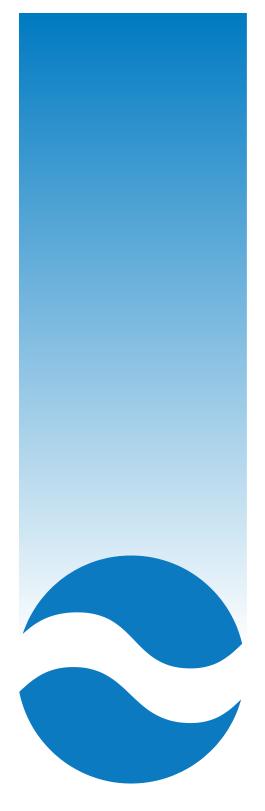
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JOINT INDUSTRY STANDARD

Handling, Packing, Shipping and Use of Moisture, Reflow, and Process Sensitive Devices





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Users of this publication are encouraged to participate in the development of future revisions.

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